

# Product Disassembly Instructions

**Product Category:****Panel PC****Product Marketing Name / Model:****PPC-3151W /PPC-3211W**

**Purpose:** The document provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC and 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.













Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq. cm Mother board, Card Reader board, USB Daughter board, LID Daughter board	8
Batteries	All types including standard alkaline and lithium coin or button style batteries 6cell battery or 9 cell battery, and RTC battery	1
External electrical cables and Power cord		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Gas Discharge Lamps		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0

Item Description	Notes	Quantity of items included in product
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Capacitors / condensers (Containing PCB)		0

Plastics containing Brominated Flame Retardants weighing > 25 grams	(Not including PCBs or PCAs already listed as a separate item above)	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Asbestos waste and components which contain asbestos		0
Components containing refractory ceramic fibers		0
Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons(HFC), hydrocarbons (HC)		0
Components, parts and materials containing radioactive substances		0

## 2.0 Disassembly Tool

List the tools that would typically be used to disassemble the product to a point where components and materials can be removed.

Disassembly Tool	Picture
Screwdriver	 
Lever	 
Star Screwdriver	 
Hexagon Driver	 
Slanted pliers	
Pliers	
Hammer	
Knife	

### **3.0 Product Disassembly Process**

3.1 List the basic steps that should typically be followed to remove components and materials.

#### **A. Disassembly Box module.**

- A-1. Disassembly 14 pcs screw to remove the Rear cover.
- A -2. Disassembly 4 pcs screw to remove the VESA&HDD module.
- A -3. Disassembly 7 pcs screw to remove the CPU heatsink.
- A -4. Disassembly Hex 6pcs from DB9/DB15 port, screw 2pcs from IO bracket to separate the IO bracket.
- A -5. Disassembly 1 pcs screw to remove the PCIe/PCI Module.
- A -6. Disassembly M.2 card (1pcs screw) and Mini PCIe card (2pcs screw) from each socket.
- A -7. Disassembly DDR module from DDR socket.
- A -8. Disassembly 3 pcs screw to remove the Mother board.
- A -9. Disassembly 4 pcs screw to remove the speaker module.
- A -10. Disassembly 4 pcs screw to remove the Control board.
- A -11. Disassembly 2 pcs Antenna rubber.

#### **B. Disassembly Panel module.**

- B -1. Disassembly 10 pcs screw to remove the Main Board frame.
- B -2. Disassembly 2 pcs screw to remove the Side I/O Bracket.
- B -3. Disassembly 1 pcs screw to remove the LED indicator light.
- B-4. Disassembly screw 4pcs to remove the LCD sub-assembly from Front Bezel.
- B-5. Disassembly screw 4pcs to Quick installation key.
- B-6. Remove the waterproof from front bezel.

3.2 Exploded view drawing. Insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

